



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20221122000.0
TSSOP and SOT Symbolization update for select devices
Information Only

Date: November 28, 2022
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20221122000.0
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) / sixty (60) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CD4066BPWR	null
LM324PW	null
OPA4170AIPW	null
SN74HC08PW	null
TXS0104EPWR	null

Technical details of this Product Change follow on the next page(s).



PCN Number:	20221122000.0	PCN Date:	November 28, 2022
Title:	TSSOP and SOT Symbolization update for select devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Datasheet
<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Part number change

PCN Details





Description of Change:

This letter is to inform customers of a device symbolization change for select devices in the TSSOP and SOT packages that will enable enhanced device level traceability.

TSSOP Package Device

	Current	Proposed
		
Pin 1 Mark	Embossed	Dot
TI Logo	With	TI letter
ECAT value	G4	None
Unit ID Coordinate	None	With

SOT-SC70 Package Device

	Current	Proposed
	 <p>**** = BINARY DATECODE CODE  = PIN 1 STRIPE</p>	 <p>**** = BINARY DATECODE CODE  = PIN 1 DOT</p>
Pin 1 Mark	Stripe	Dot

Reason for Change:

Improved Device traceability

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

None

Product Affected: TSSOP Package

Refer to page 2 of this document to view your affected products

Product Affected: SOT-SC70 Package

TMUX1101DCKR	TMUX1219DCKR	TMUX1247DCKR
TMUX1102DCKR	TMUX1237DCKR	TMUX1248DCKR
TMUX1119DCKR	TMUX1238DCKR	TMUX4157NDCKR

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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